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TO THE HONORABLE DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE. PLEASE RECORD THE ATTACHED ORIGINAL DOCUMENTS OR COPY THEREOF.

1. Name of conveying party(ies):

- (a) Seong Min Seo
(b) Young Suk Chung
(c) Jong Sik Paek

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: Amkor Technology, inc.

Street Address: 1900 South Price Road

City: Chandler

AZ

85248-1604

Country: U.S.A.

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: March 15, 2001

Name and address of receiving party(ies):

Name: {Enter Name}

Street Address: {Enter Street Address}

City: {City}

State: {State}

Zip: {Zip}

Country: {Country}

Additional name(s) & address(es) attached?

☐ Yes ☒ No

4. Application number(s) or patent number(s):

09 816 599

If this document is being filed together with a new application, the execution date of the application is: March 15, 2001

A. Patent Application No.(s) - {Patent Application Numbers}

Title: Semiconductor Package Including Stacked Chips

B. Patent No.(s)

Additional numbers attached?

☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: James E. Parsons

Internal Address: SKJERVEN MORRILL MacPHERSON LLP

Street Address: 25 METRO DRIVE, SUITE 700

City: SAN JOSE State: CA Zip: 95110

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

- ☒ Authorized to be charged to Deposit Account 19-2386
☒ Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

James E. Parsons 34,691
Name of Person Signing

Signature

March 23, 2001
Date

Total number of pages comprising cover sheet: 4

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we


<u>Seong Min Seo</u>	of <u>Seoul, Republic of Korea</u>
<u>Young Suk Chung</u>	of <u>Seoul, Republic of Korea</u>
<u>Jong Sik Paek</u>	of <u>Seoul, Republic of Korea</u>
<u>Jae Hun Ku</u>	of <u>Singapore</u>
<u>Jae Hak Yee</u>	of <u>Singapore</u>

hereby sell, assign and transfer to Amkor Technology, Inc., a Delaware corporation, having a place of business at 1900 South Price Road, Chandler, AZ 85248-1604, its successors and assigns, the entire right, title and interest throughout the world in our invention in:

Semiconductor Package Including Stacked Chips

for which we have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; we authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from us; we agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and we request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 15 day of March, 2001.



Seong Min Seo

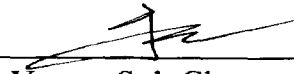
WITNESSED:

Signature

Date

Type or print name of witness

Executed this 15 day of March, 2001.



Young Suk Chung

WITNESSED:

Signature

Date

Type or print name of witness

Executed this 15 day of March, 2001.



Jong Sik Paek

WITNESSED:

Signature

Date

Type or print name of witness

Executed this _____ day of _____, 2001.

Jae Hun Ku

WITNESSED:

Signature

Date

Type or print name of witness

Executed this _____ day of _____, 2001.

Jae Hak Yee

WITNESSED:

Signature

Date

Type or print name of witness